

# Product / Process Change Notification



N° 2020-072-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Introduction of an additional assembly and final test location for dedicated OPTIMOS products in TO252-3 package at Tongfu Microelectronics Co., Ltd., China

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **29. October 2020**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:  
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.


Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
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Chairman of the Supervisory Board: Dr. Wolfgang Eder  
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider  
Registered Office: Neubiberg  
Commercial Register: München HRB 126492

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► **Products affected:** Please refer to attached affected product list 1\_cip20072\_a 

► **Detailed Change Information:**

**Subject:** Introduction of an additional assembly and final test location for dedicated OPTIMOS products in TO252-3 package at Tongfu Microelectronics Co., Ltd., China

**Reason:** Expansion of assembly and final test to assure continuity of supply and enable flexible manufacturing.

<b>Description:</b>	<b>Old</b>	<b>New</b>
Assembly and final test location	<ul style="list-style-type: none"><li>Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia</li></ul>	<ul style="list-style-type: none"><li>Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia</li><li>Tongfu Microelectronics Co., Ltd., China</li></ul>
Mold compound	<ul style="list-style-type: none"><li>Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia Mold compound = CEL800</li></ul>	<ul style="list-style-type: none"><li>Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia Mold compound = CEL800</li><li>Tongfu Microelectronics Co., Ltd., China Mold compound = CEL9220</li></ul>
Package outline	<ul style="list-style-type: none"><li>Please refer to attachment 3_cip20072_a</li></ul>	<ul style="list-style-type: none"><li>Please refer to attachment 3_cip20072_a</li></ul>

► **Product Identification:** Internal traceability via Baunumber, Lotnumber, date code and marking on device  
External traceability via marking on device

► **Impact of Change:** **NO** change on electrical and thermal performance  
**NO** impact on the device reliability as proven via product qualification and characterization.  
**NO** impact on the electrical parameters and device processability at customer end. Assembly processes are optimized to meet product performance according to already applied Infineon specification.

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## ► Attachments:

Affected product list : 1\_cip20072\_a  
Qualification report : 2\_cip20072\_a  
Customer info package : 3\_cip20072\_a

## ► Time Schedule:

- |                               |  |
|-------------------------------|--|
| ■ Final qualification report: | available  |
| ■ First samples available:    | on request   |
| ■ Intended start of delivery: | 21-Dec-2020 or earlier, depending on customer approval |

If you have any questions, please do not hesitate to contact your local Sales office.